	CONNECTING CS INDUSTRIES	PC, Bannockb	ourn, Illinois. A	All rights reserved un ntions.	nder both	This docume level parts, t	ent is a declarat he declaration e	ion of th encompa	ne substances asses all low	within the er level mat	manufactur erials for wl	er listed it hich the m	tem. Note: if nanufacturer	the item is an as has engineering	ssembly with low responsibility.	
752-21.1					Form Type Distribute	e * Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mate					eous Materia	rials and Mfg Information				
upplie	r Information															
ompany	name*	Company unique ID			1	Unique ID Authority					Response Date*					
nsemi												2025-09-14				
ontact N	lame	Title - Contact			]	Phone - Contact*				Email - Contact*						
roduct-	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com						
uthorize	ed Representative*	Title - Representative			]	Phone - Representative*				Email - Representative*						
roduct-	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com						
	Requester Item Number Mfr Item   FDH363		Number Mfr Item Name				Effective Date	Effective Date Version Manufacturing		ing Site	Weight*		UOM	Unit Type		
			2	FET 100V 9.0 mOhm TO247			2025-09-14 CP8			4	5431.175	mg	Each			
Ianufa	cturing Proccess Informa	tion														
	Terminal Plating / Grid Array Material		Ferminal Base Alloy J-STD-020 M		-STD-020 MSI	L Rating	Peak Process Body Temperatu		ure Max Time at Peak Temper		Temperat	ure Numb	er of Reflow Cy	cles		
	Matte Tin (Sn) - annealed		CU Alloy NA			0 C		30 seco		secon	ds 3					
omments	3															
or more	information regarding material	composition	please refer to	o page 3												

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et	
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 4 - Item(	s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).		
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the
Supplier Digital Signature	astislav Drska	Le			

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	6.45	mg	Supplier	Silicon (Si)	7440-21-3		6.45	mg
Die Attach Solder	35.025	mg	Supplier	Silver (Ag)	7440-22-4		0.8756	mg
			А	Lead (Pb)	7439-92-1	7a	32.3981	mg
			Supplier	Tin (Sn)	7440-31-5		1.7512	mg
ead Frame	3612.9	mg	Supplier	Zinc (Zn)	7440-66-6		1.75	mg
			В	Nickel (Ni)	7440-02-0		117.9998	mg
			Supplier	Iron (Fe)	7439-89-6		2.1	mg
			Supplier	Copper (Cu)	7440-50-8		3489.9998	mg
			Supplier	Phosphorus (P)	7723-14-0		1.05	mg
Aold Compound-Black	1739.8	mg	Supplier	Polymer(phenyl glycidil ether)-co- dicyclopentadiene	119345-05-0		86.99	mg
			Supplier	Proprietary	Proprietary Data		86.99	mg
			Supplier	Carbon Black (C)	1333-86-4		8.699	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		78.291	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		1304.8501	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		86.99	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		86.99	mg
Plating	31.0	mg	Supplier	Tin (Sn)	7440-31-5		31	mg
Wire Bond - Al	6.0	mg	Supplier	Aluminum (Al)	7429-90-5		6	mg